Notice of References Cited					Application No. 09/114,66	<	Applicant(s)	Bieles	eta	l
					Examiner			Group Art Unit		
					S. Ip 174			1742	Page of	
U.S. PATENT DOCUMENTS										
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Γ				NON-PA	TENT DOCUMENT	rs			· ·	
*		DOCUMENT (Including Author, Title, Source, and Pertinent Pages)								
Γ	Gibson, A.W.; Choi, S.L.; Subramanian, K. N.) Bieles, T.R., Issues usegarding microstructural coarsening due to agin a of entectic									1997
	U	regarding microstructural coarsening due to aging of entectic								
H	\vdash	tin-silver solder, Des. Reliab. Solders Solder Interconnect, Proc. Symp. (1997), 97-103.								
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